

[illegible]

FIG.2

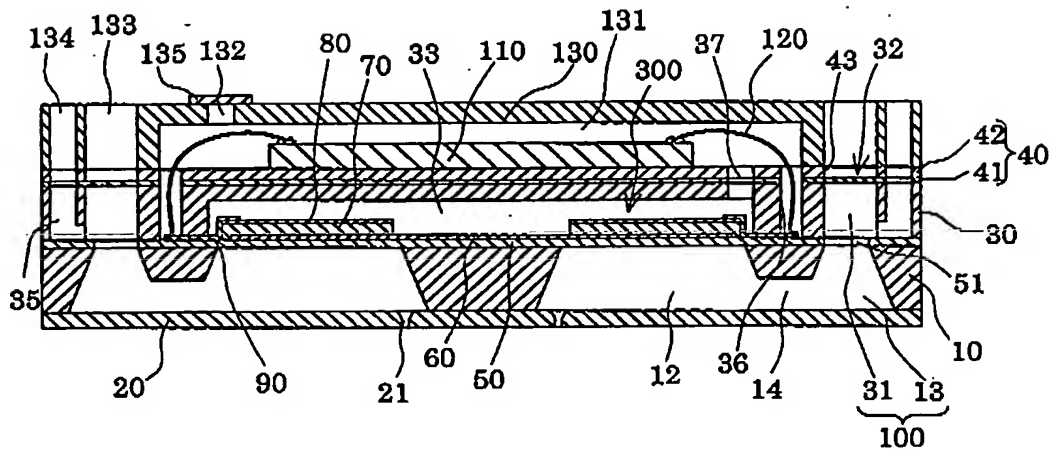
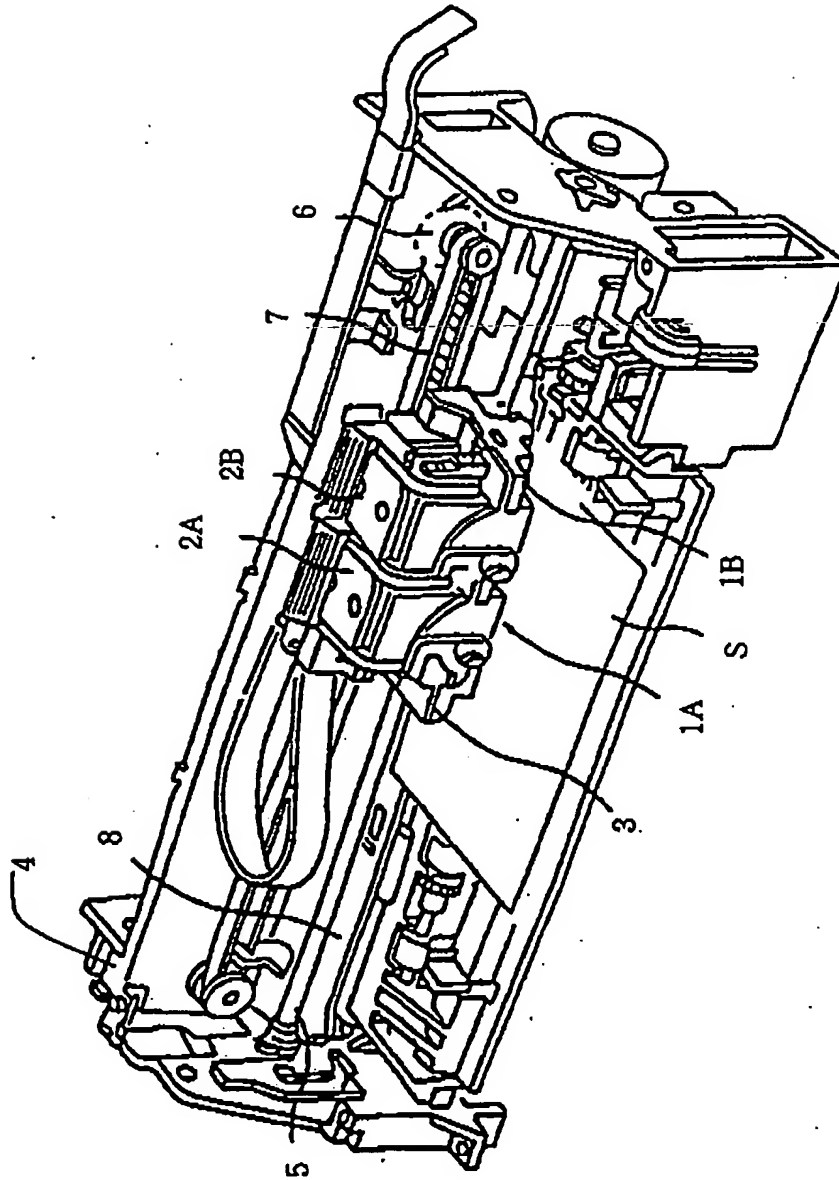


FIG.3





This cross-sectional diagram illustrates a multi-layered semiconductor assembly. At the base is a substrate 10 with a central opening 12. A layer 18 is formed over the substrate, containing features 13 and 31. Above this is a layer 30 with openings 14 and 51. A core layer 40 contains a central channel 41 and side regions 42. This core is flanked by vertical structures 36 and 37. The top section consists of a patterned layer 120, a thick insulating or protective layer 140, and a final top layer 141(170). Various other components are labeled with reference numerals such as 20, 90, 70, 80, 21, 60, 50, 110, 130, 300, 131(170), 132, 180, 33(170), and 133.

FIG. 6

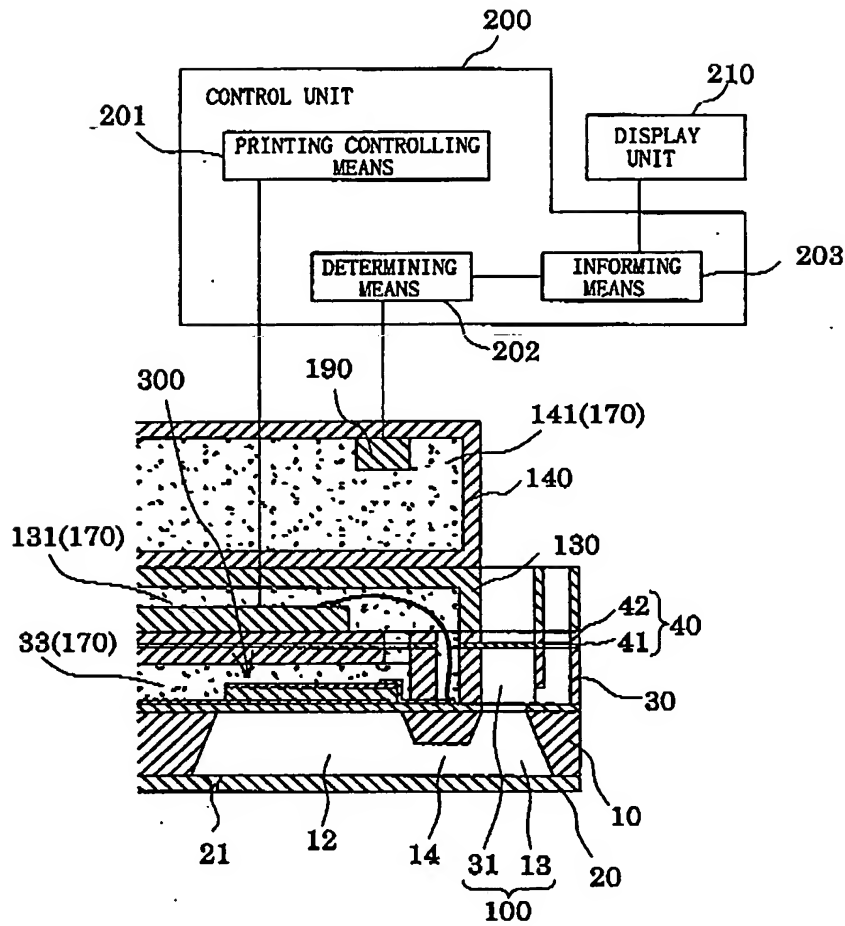


FIG. 7

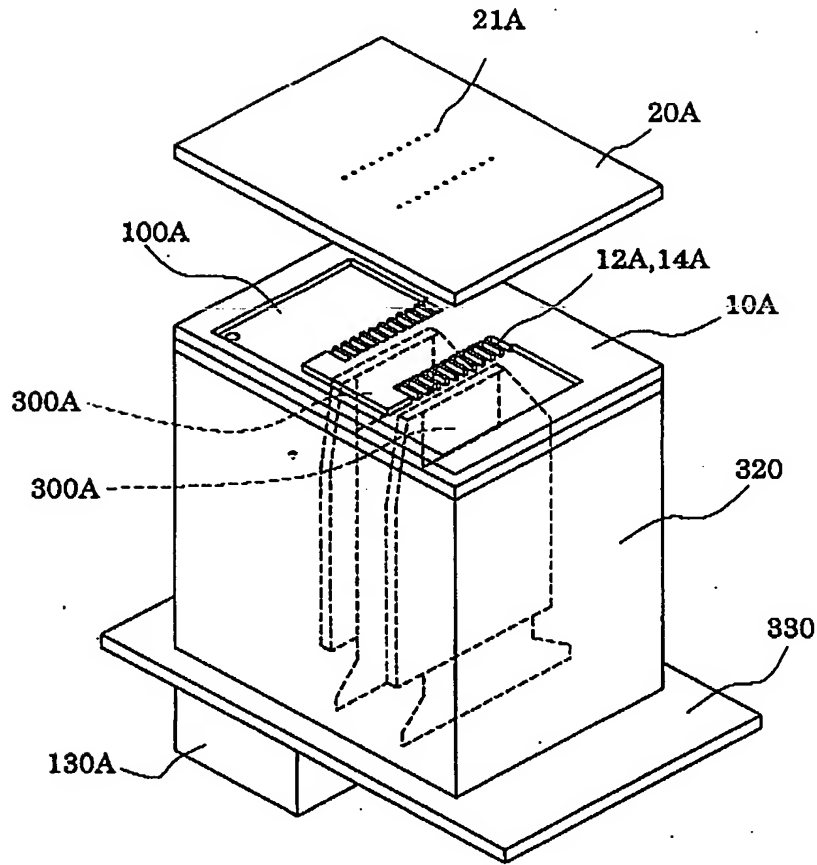


FIG.8

